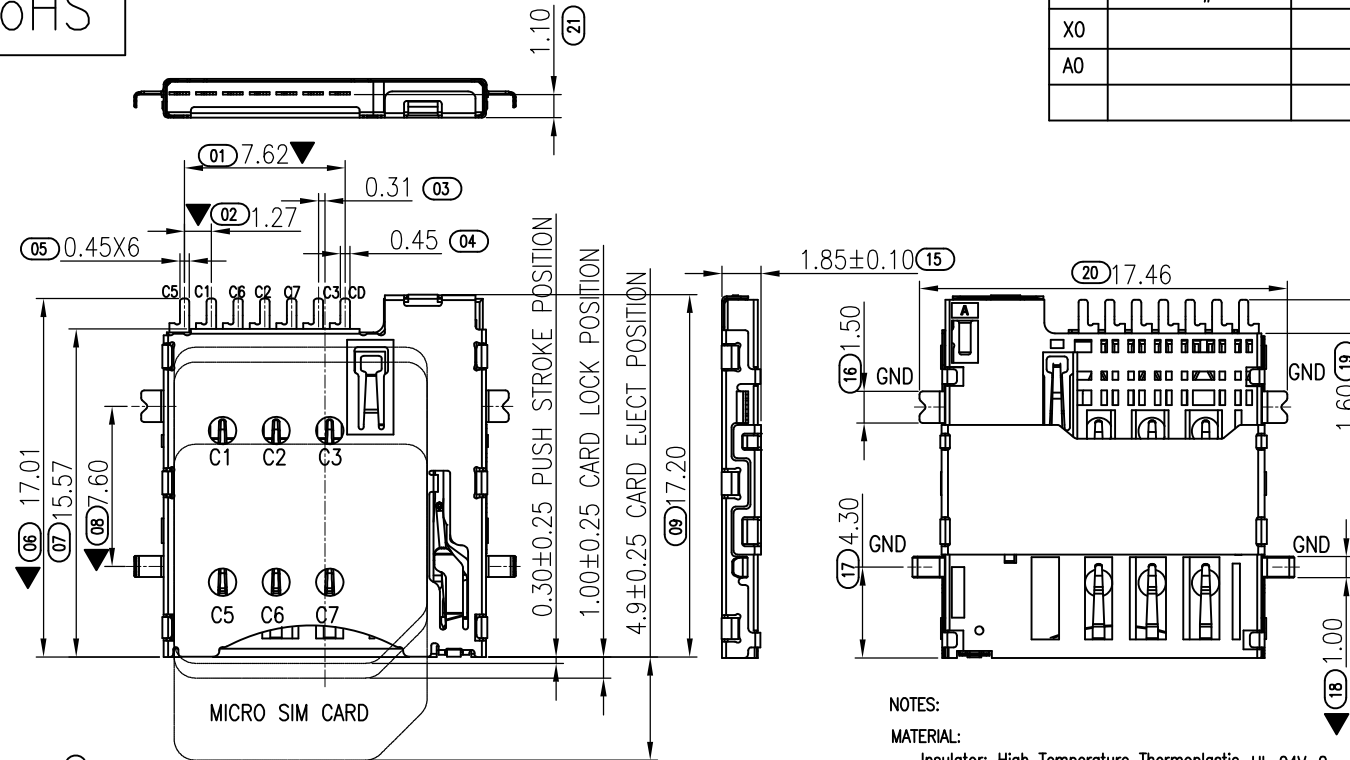


RoHS

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
X0		NEW RELEASE	20171020	YANG		HAIYONG
A0		Fixed LAYOUT	20180115	TEDDY		HAIYONG



NOTES:

MATERIAL:

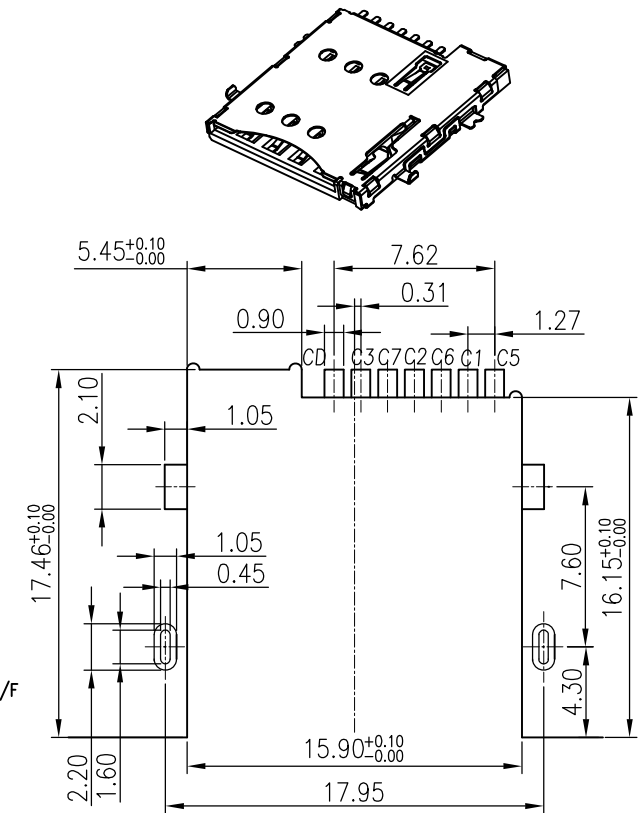
Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
Shell: STAINLESS

PLATING:

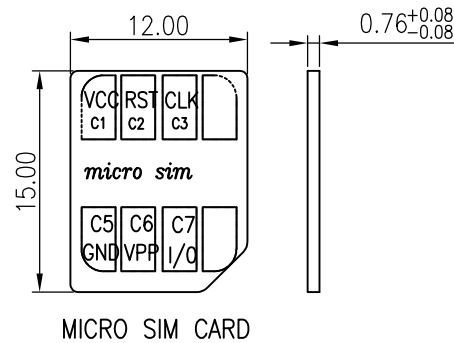
Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature:260°C ±5°



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

MILLIMETERS	INCH	UNITS	MM	XG 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.	
X° ± 2°	X° ±	MAT'L			
.X ± 0.30	.XX ±	SEE NOTES		PART NUMBER: XB-102322222	TITLE: MICRO-SIM PUSH/PUSH 6PIN 1.35H 带CD PIN (有弹片) 反沉1.1
.XX ± 0.20	.XXX ±	FINISH		APPD:	DWG NO.: C-10232222-00
.XXX ± 0.10	.XXXX ±	SEE NOTES		CHKD:	
		QTY		DR:	
		SEE NOTES			